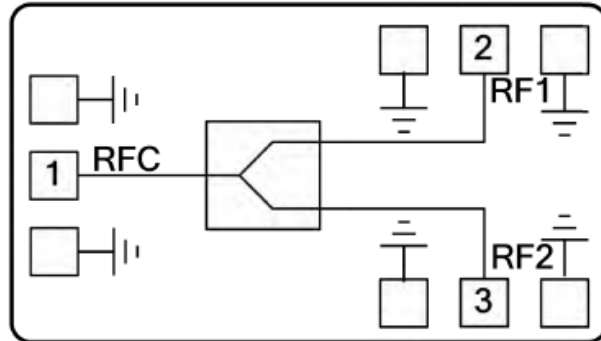




Features

- Frequency: 18-26GHz
- Insertion Loss: 0.4dB Typical
- Isolation: 23dB Typical
- Input/Output: 50Ω
- Chip Size: 0.965 x 0.965 x 0.1mm

Functional Block Diagram



Typical Applications

- Test Instrumentation
- Microwave Radio & VSAT
- Military & Space
- Telecom Infrastructure
- Fiber Optics

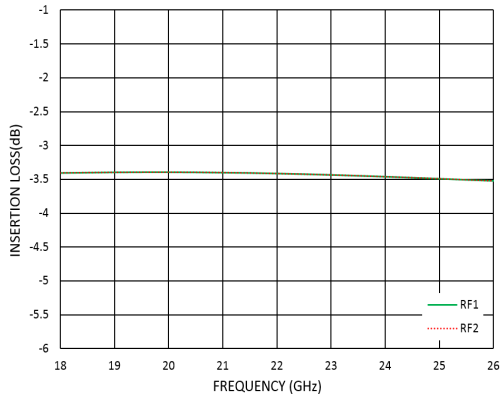
Electrical Specifications

TA = +25°C ,Pin=0dBm

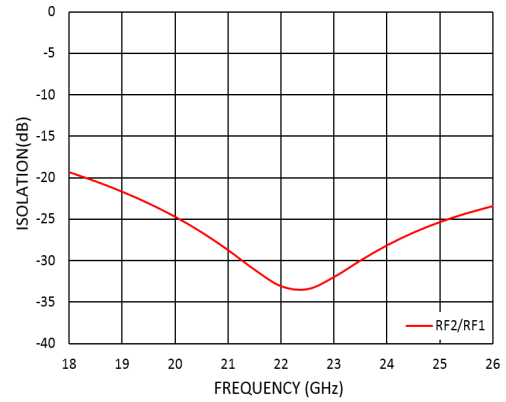
| Parameters | Min. | Typ. | Max. | Units |
|-------------------------|------|------|------|-------|
| Frequency | 18 | | 26 | GHz |
| Nominal Splitter Loss | | 3 | | dB |
| Insertion Loss | | 0.4 | 0.6 | dB |
| Insertion Loss Flatness | | ±0.1 | | dB |
| Isolation | 18 | 23 | | dB |
| Input Return Loss | 17 | 22 | | dB |
| Output Return Loss | 21 | 25 | | dB |



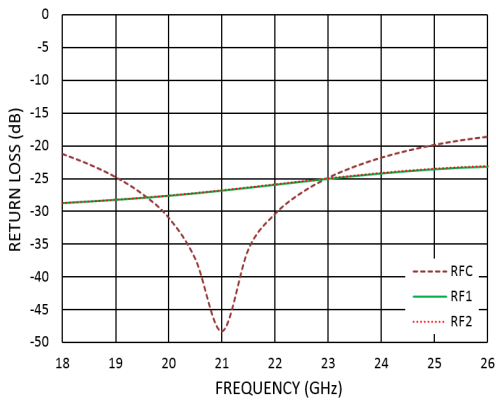
Insertion Loss vs. Frequency



Isolation vs. Frequency

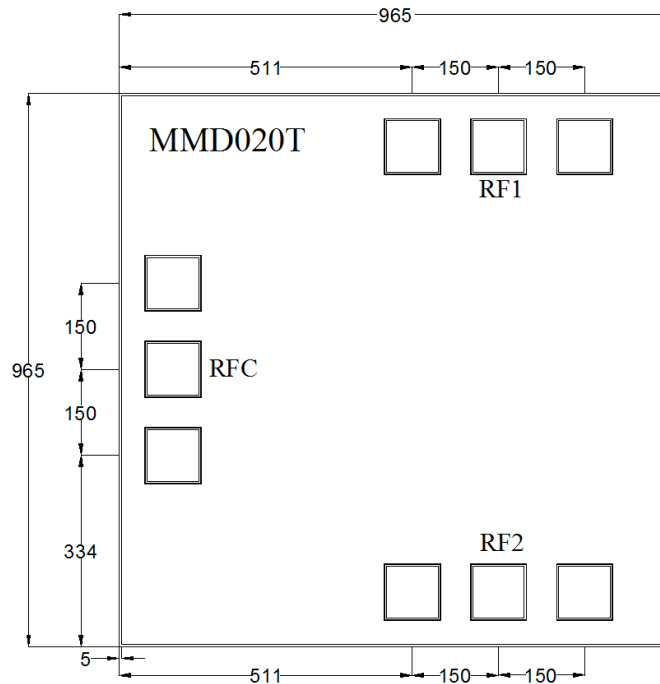


Return Loss vs. Frequency





Outline Drawing: All Dimensions in μm



Absolute Maximum Ratings

| | |
|-----------------------|------------------|
| RF Input Power | +40dBm |
| Operating Temperature | -55°C to +85 °C |
| Storage Temperature | -65°C to +150 °C |

| No | Symbol | Description |
|-----|---------|-----------------|
| 1 | RFC | RF Common Port |
| 2,3 | RF1&RF2 | RF Branch Ports |

Notes:

1. Die thickness: 100 μm
2. RF IN/OUT bond pad is 100*100 μm^2
3. Bond pad metalization: Gold
4. Backside metalization: Gold
5. Backside of the die (GND)

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